

FOR IMMEDIATE RELEASE

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SIX SIGMA Achieves ISO 9001:2008 Certification

MILPITAS, Calif. – Oct. 29, 2009 – SIX SIGMA (a business unit of Winslow Automation, Inc.) announced achievement of ISO 9001:2008 certification for its quality management system only one year after it achieved its AS9100 and ISO 9001:2000 certification. SIX SIGMA is a leading provider of column attach, robotic solder dip, BGA reballing, and failure analysis services for the electronic component packaging industry.

About SIX SIGMA

SIX SIGMA provides services for the alteration of microelectronic components for use in high-reliability, military, and aerospace applications. SIX SIGMA was founded in 1990 as a service division of Winslow Automation, Inc. (Winslow Automation, Inc. dba SIX SIGMA) providing robotic hot solder dipping (lead finish) services and related testing for the semiconductor and printed circuit board industries. Today, SIX SIGMA's multi-million dollar custom-designed facility is located in the heart of the fast-paced, cutting-edge Silicon Valley. Primary services include; column attach, ball attach, hot solder dip, environmental testing and failure analysis. In addition, SIX SIGMA holds DSCC commercial laboratory suitability status for hermeticity testing, and DSCC transitional QML status for its robotic hot solder dip and column attach services. Components processed by SIX SIGMA are in applications that vary from the most sophisticated missile guidance systems, to the engine controllers in commercial airlines, to automobile passive restraint systems. Today, SIX SIGMA is a recognized leader in semiconductor lead finish - processing millions of high-reliability semiconductor components each year.

For additional information on our services, please contact us at (408) 956-0100 and visit our web site at www.sixsigmaservices.com.